# EVERLIGHT ELECTRONICS CO.,LTD.

### **Technical Data Sheet**

# 0603 Package Chip LED(0.6mm Height)

### 19-213/G6C-AP1Q2/3T

#### **Features**

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.

#### **Descriptions**

- The 19-213 SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

#### **Applications**

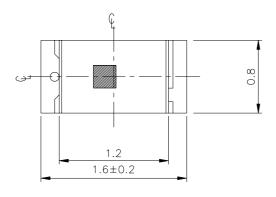
- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

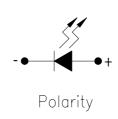
### **Device Selection Guide**

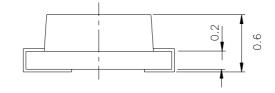
DA DE NO		T 0.1	
PART NO.	Material	<b>Emitted Color</b>	Lens Color
19-213/G6C-AP1Q2/3T	AlGaInP	Brilliant Yellow Green	Water Clear



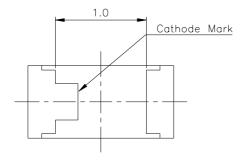
### **Package Outline Dimensions**

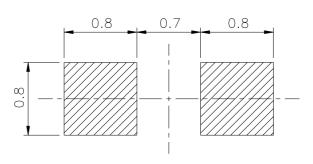






For reflow soldering (Propose)





**Note:** Tolerances Unless Dimension is  $\pm 0.1$ mm, Unit = mm

### **Absolute Maximum Ratings (Ta=25°C)**

Parameter	Symbol	Rating	Unit	
Reverse Voltage	$V_R$	5	V	
Forward Current	$I_{\mathrm{F}}$	25	mA	
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\!\mathbb{C}$	
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}\!\mathbb{C}$	
Electrostatic Discharge	ESD	2000	V	
Power Dissipation	Pd	60	mW	
Peak Forward Current (Duty 1/10 @1KHz)	IFP	60	mA	
Soldering Temperature	Tsol	Reflow Soldering : 260°C for 10sec. Hand Soldering : 350°C for 3 sec.		

### **Electro-Optical Characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	$I_V$	45.0		112	mcd	
Viewing Angle	2 \theta 1/2		120		deg	
Peak Wavelength	λр		575		nm	
Dominant Wavelength	λd	569.5		577.5	nm	$I_F = 20 \text{mA}$
Spectrum Radiation Bandwidth	Δλ		20		nm	
Forward Voltage	$V_{\mathrm{F}}$		2.0	2.4	V	
Reverse Current	$I_R$			10	$\mu$ A	V <sub>R</sub> =5V

#### **Notes:**

- 1.Tolerance of Luminous Intensity ±10%
- 2.Tolerance of Dominant Wavelength ±1nm
- 3.Tolerance of Forward Voltage ±0.1V

### Bin Range Of Dom. Wavelength

Group	Bin	Min	Max	Unit	Condition	
A	C16	569.5	571.5			
	C17	571.5	573.5		1 20 4	
	C18	573.5	575.5	nm	$I_F=20mA$	
	C19	575.5	577.5			

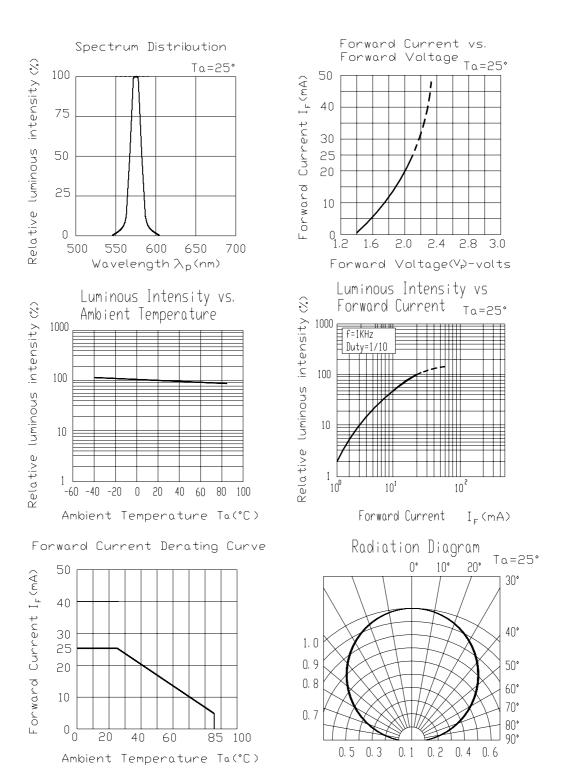
### **Bin Range Of Luminous Intensity**

Bin	Min	Max	Unit	Condition
P1	45.0	57.0		
P2	57.0	72.0	,	1 20 4
Q1	72.0	90.0	mcd	I <sub>F</sub> =20mA
Q2	90.0	112		

#### **Notes:**

- 1.Tolerance of Luminous Intensity ±10%
- 2.Tolerance of Dominant Wavelength ±1nm

### **Typical Electro-Optical Characteristics Curves**



### Label explanation

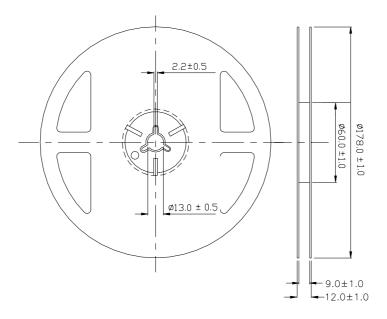
**CAT: Luminous Intensity Rank** 

**HUE: Dom. Wavelength Rank** 

**REF: Forward Voltage Rank** 

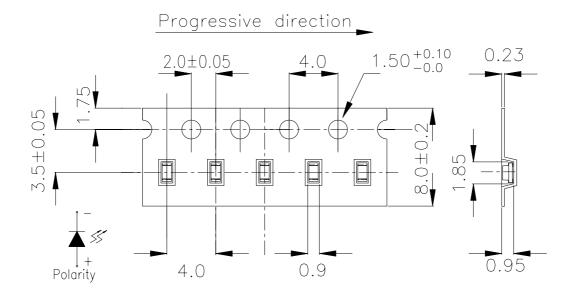


#### **Reel Dimensions**



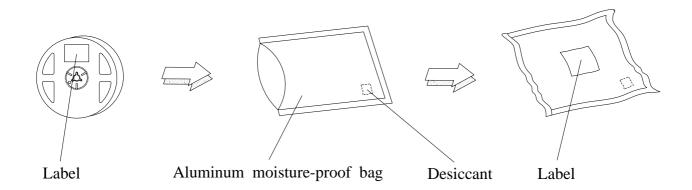
**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm, Unit = mm.

### Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm, Unit = mm.

### **Moisture Resistant Packaging**



### **Reliability Test Items And Conditions**

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

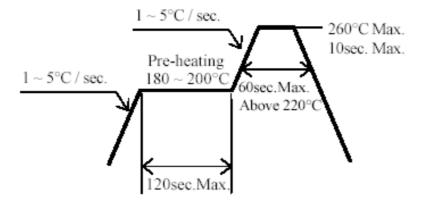
No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C 5 sec.	6 Min.	22 Pcs.	0/1
2	Temperature Cycle	$H: +100^{\circ}\mathbb{C}$ 15min $\int$ 5 min $L: -40^{\circ}\mathbb{C}$ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H:+100°C 5min ∫ 10 sec L:-10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°℃	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C/85%RH	1000 Hrs.	22 PCS.	0/1

#### **Precautions For Use**

- 1. Over-current-proof
  - Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).
- 2. Storage
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less(Floor life). However,it's recommended that The LEDs should be used within 168 hours (7 days) after opening the package. If unused LED remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment :  $60\pm5^{\circ}$ C for 24 hours.

- 3. Soldering Condition
- 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.
- 4. Soldering Iron

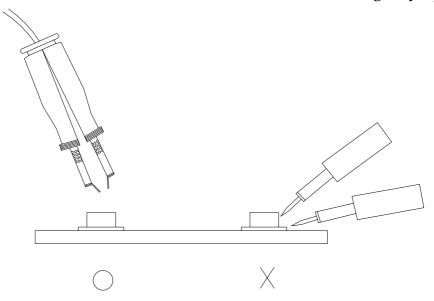
Each terminal is to go to the tip of soldering iron temperature less than  $350^{\circ}$ C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

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#### 5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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